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Docket No.: 1381.1005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Shunji BABA et al.

Serial No. 09/753,570

Group Art Unit: 2812

Confirmation No. 2008

Filed: January 4, 2001

Examiner: Angel Roman

For: METHOD OF MOUNTING CHIP ONTO PRINTED CIRCUIT BOARD IN SHORTENED  
WORKING TIME

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TECHNOLOGY CENTER 2800

AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

This is in response to the Office Action mailed November 1, 2002, and having a period for response set to expire on February 1, 2003.

The following amendments and remarks are respectfully submitted. Reconsideration of the claims is respectfully requested.

IN THE SPECIFICATION:

Please REPLACE the paragraph beginning at page 27, line 28, with the following paragraph:

B' An electromagnetic wave is then irradiated on the silicon wafer 23. An infrared source 74 may be employed to irradiate the electromagnetic wave. An infrared ray irradiated from the infrared source 74 sequentially passes or penetrates through the silicon wafer 23, the underfill material sheet 67 and the thin film member 66. An infrared camera 75 is designed to capture the penetrating infrared ray below the second platen 72. The infrared camera 75 detects the shadow of the input/output bumps 59 which blocks out transmission of the infrared ray. The shadow of the input/output bumps 59 is utilized to determine the cutting position on the silicon